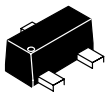
General Purpose Transistor

NPN Silicon

These transistors are designed for general purpose amplifier applications. They are housed in the SC−89 package which is designed for low power surface mount applications.

LMBT2222ATT1G
S-LMBT2222ATT1G



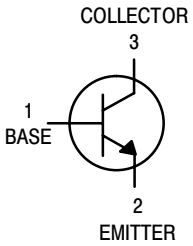
SC-89

Features

- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

ORDERING INFORMATION

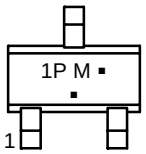
Device	Maring	Shipping†
LMBT2222ATT1G S-LMBT2222ATT1G	1P 1P	3000 / Tape & Reel
LMBT2222ATT3G S-LMBT2222ATT3G	1P 1P	10000 / Tape & Reel



MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector−Emitter Voltage	V_{CEO}	40	Vdc
Collector−Base Voltage	V_{CBO}	75	Vdc
Emitter−Base Voltage	V_{EBO}	6.0	Vdc
Collector Current − Continuous	I_C	600	mAdc

MARKING DIAGRAM



1P = Specific Device Code
M = Date Code
▪ = Pb−Free Package

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation (Note 1) T_A = 25°C	P_D	150	mW
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	833	°C/W
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector−Emitter Breakdown Voltage (Note 1) (I_C = 1.0 mAdc, I_B = 0)	$V_{(BR)CEO}$	40	−	Vdc
Collector−Base Breakdown Voltage (I_C = 10 μAdc, I_E = 0)	$V_{(BR)CBO}$	75	−	Vdc
Emitter−Base Breakdown Voltage (I_E = 10 μAdc, I_C = 0)	$V_{(BR)EBO}$	6.0	−	Vdc
Base Cutoff Current (V_{CE} = 60 Vdc, V_{EB} = 3.0 Vdc)	I_{BL}	−	20	nAdc
Collector Cutoff Current (V_{CE} = 60 Vdc, V_{EB} = 3.0 Vdc)	I_{CEX}	−	100	nAdc

ON CHARACTERISTICS (Note 2)

DC Current Gain (I_C = 0.1 mAdc, V_{CE} = 10 Vdc) (I_C = 1.0 mAdc, V_{CE} = 10 Vdc) (I_C = 10 mAdc, V_{CE} = 10 Vdc) (I_C = 150 mAdc, V_{CE} = 10 Vdc) (I_C = 500 mAdc, V_{CE} = 10 Vdc)	H_{FE}	 35 50 75 100 40	 – – – – –	–
Collector−Emitter Saturation Voltage (I_C = 150 mAdc, I_B = 15 mAdc) (I_C = 500 mAdc, I_B = 50 mAdc)	$V_{CE(sat)}$	 – –	 0.3 1.0	Vdc
Base−Emitter Saturation Voltage (I_C = 150 mAdc, I_B = 15 mAdc) (I_C = 500 mAdc, I_B = 50 mAdc)	$V_{BE(sat)}$	 0.6 –	 1.2 2.0	Vdc

SMALL−SIGNAL CHARACTERISTICS

Current−Gain − Bandwidth Product (I_C = 20 mAdc, V_{CE} = 20 Vdc, f = 100 MHz)	f_T	250	–	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)	C_{obo}	–	8.0	pF
Input Capacitance (V_{EB} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)	C_{ibo}	–	30	pF
Input Impedance (V_{CE} = 10 Vdc, I_C = 10 mAdc, f = 1.0 kHz)	h_{ie}	0.25	1.25	kΩ
Voltage Feedback Ratio (V_{CE} = 10 Vdc, I_C = 10 mAdc, f = 1.0 kHz)	h_{re}	–	4.0	X 10^{-4}
Small−Signal Current Gain (V_{CE} = 10 Vdc, I_C = 10 mAdc, f = 1.0 kHz)	h_{fe}	75	375	–
Output Admittance (V_{CE} = 10 Vdc, I_C = 10 mAdc, f = 1.0 kHz)	h_{oe}	25	200	μmhos
Noise Figure (V_{CE} = 10 Vdc, I_C = 100 μAdc, R_S = 1.0 k ohms, f = 1.0 kHz)	NF	–	4.0	dB

SWITCHING CHARACTERISTICS

Delay Time	(V_{CC} = 3.0 Vdc, V_{BE} = −0.5 Vdc, I_C = 150 mAdc, I_{B1} = 15 mAdc)	t_d	–	10	ns
Rise Time		t_r	–	25	
Storage Time	(V_{CC} = 30 Vdc, I_C = 150 mAdc, I_{B1} = I_{B2} = 15 mAdc)	t_s	–	225	ns
Fall Time		t_f	–	60	

1. Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.
2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

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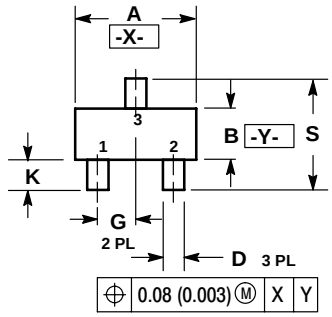
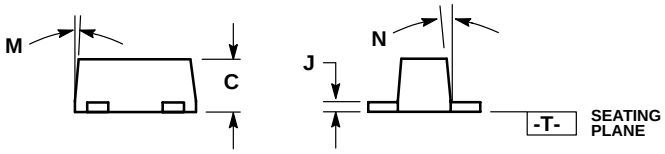
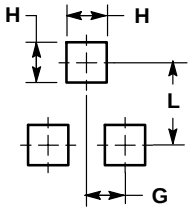
SC−89





NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
H	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M	---	---	10 °	---	---	10 °
N	---	---	10 °	---	---	10 °
S	1.50	1.60	1.70	0.059	0.063	0.067



RECOMMENDED PATTERN OF SOLDER PADS